Response to Amendment

This is in response to the Amendment filed 16 March 2004.

Specification

1. The objection to the disclosure because of minor informalities has been withdrawn in view of Applicants' Amendment.

Drawings

- 2. The objection to the drawings as failing to comply with 37 CFR 1.84(p)(4) because the same reference character has been used to designate different parts has been withdrawn in view of Applicants' Amendment.
- 3. The objection to the drawings as failing to comply with 37 CFR 1.84(p)(5) because they do not include reference sign(s) mentioned in the description has been **withdrawn** in view of Applicants' Amendment.
- 4. The objection to Figures 13-15 for not being designated by a legend such as --Prior Art-because only that which is old is illustrated has been **withdrawn** in view of Applicants' Amendment.

Claim Rejections - 35 USC § 112

5. The rejection of claims 1-2 under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention has been withdrawn in view of Applicants' Amendment.

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Claim Rejections - 35 USC § 102

6. The rejection of claim 1 under 35 U.S.C. 102(b) as being anticipated by Applicants' Prior Art Figures has been withdrawn in view of Applicants' Amendment.

Allowable Subject Matter

7. Claims 1-5 are allowable over the prior art of record.

Reasons for Allowance

8. The following is an examiner's statement of reasons for allowance:

The claimed invention includes at least two protrusions that protrude toward opposite sides which appear upon at-a-right-angle projection of a second substrate onto a first substrate, and a method of using the same to assembly a thermoelectric module in a radiating member. The Applicants disclose that because of the protrusions support arms push the respective protrusions of the first substrate under pressure to push the first substrate toward the radiating member without being slanted or rock the first substrate in the direction orthogonal to the pushing direction, thereby being capable of bonding a first substrate to the radiating member through melted solder. Since forces for pushing and rocking the first substrate are transmitted not through the thermoelectric semiconductor chips but directly to the first substrate from the respective protrusions, the bonding portions of the thermoelectric semiconductor chips and the electrodes through the first solder are not broken, and accordingly there is no fear that the thermoelectric module is broken. Further, the Applicants provide comparative data comparing the instantly claimed thermoelectric module and method of making the same with a prior art thermoelectric

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module and corresponding prior art method of making the same wherein the module has only one protrusion. The data show that the instantly claimed module can be assembled without being broken.

Therefore, a search of the prior art of record failed to reveal or explicitly teach what is instantly claimed: in particular,

A thermoelectric module, comprising: a plurality of thermoelectric semiconductor chips; first and second substrates; a plurality of first and second electrodes formed on said first and second substrates, respectively; and a first solder through which said first and second electrodes are bonded to respective end portions of said thermoelectric semiconductor chips in order to connect the plural thermoelectric semiconductor chips in series, said first substrate being made to include at least two protrusions that protrude toward opposite sides which appear upon at-a-right-angle projection of the second substrate onto the first substrate. For this reason, claim 1 and claim 2, which is dependent thereon, are patentably distinct from the prior art of record.

A method of assembling a thermoelectric module in a radiating member, comprising the steps of: mounting the first substrate of the thermoelectric module according to claim 1 on a radiating member through second solder having a liquidus temperature lower than a solidus temperature of the first solder; holding the respective protrusions of the first substrate by leading edges of corresponding support arms in a state where the second solder is melted, and pushing the first substrate toward the radiating member under pressure while rocking the first substrate in a direction orthogonal to the pushing direction. For this reason, claim 3 and claims 4-5, which are dependent thereon, are patentably distinct from the prior art of record.

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Thomas H Parsons whose telephone number is (571) 272-1290. The examiner can normally be reached on M-F (7:00-4:30) First Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Pat Ryan can be reached on (571) 272-1292. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Thomas H Parsons Examiner Art Unit 1745

CAROL CHANEY
PRIMARY EXAMINER